

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr><td>Toshinari Sasaki</td><td>11/02/2011</td></tr> <tr><td>Hitomi Sato</td><td>11/02/2011</td></tr> <tr><td>Kosei Noda</td><td>11/03/2011</td></tr> <tr><td>Yuta Endo</td><td>11/03/2011</td></tr> <tr><td>Mizuho Ikarashi</td><td>10/27/2011</td></tr> <tr><td>Keitaro Imai</td><td>10/13/2011</td></tr> <tr><td>Atsuo Isobe</td><td>11/02/2011</td></tr> <tr><td>Yutaka Okazaki</td><td>11/02/2011</td></tr> </tbody> </table>		Name	Execution Date	Toshinari Sasaki	11/02/2011	Hitomi Sato	11/02/2011	Kosei Noda	11/03/2011	Yuta Endo	11/03/2011	Mizuho Ikarashi	10/27/2011	Keitaro Imai	10/13/2011	Atsuo Isobe	11/02/2011	Yutaka Okazaki	11/02/2011
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td style="width: 20%;">Name:</td><td>Semiconductor Energy Laboratory Co., Ltd.</td></tr> <tr><td>Street Address:</td><td>398, Hase</td></tr> <tr><td>City:</td><td>Atsugi-shi, Kanagawa-ken</td></tr> <tr><td>State/Country:</td><td>JAPAN</td></tr> <tr><td>Postal Code:</td><td>243-0036</td></tr> </table>		Name:	Semiconductor Energy Laboratory Co., Ltd.	Street Address:	398, Hase	City:	Atsugi-shi, Kanagawa-ken	State/Country:	JAPAN	Postal Code:	243-0036								
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CORRESPONDENCE DATA																			
Fax Number: (703)766-2394 Phone: (571) 434-6789 Email: uspto@riplo.com <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i> Correspondent Name: Eric J. Robinson Address Line 1: Robinson IP Law Office, P.C. Address Line 2: 3975 Fair Ridge Drive, Suite 20 North Address Line 4: Fairfax, VIRGINIA 22033																			

OP \$40.00 13188992

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PATENT
 REEL: 027197 FRAME: 0273

ATTORNEY DOCKET NUMBER:	0756-9422
NAME OF SUBMITTER:	Eric J. Robinson
Total Attachments: 3 source=ASSIGNMENT#page1.tif source=ASSIGNMENT#page2.tif source=ASSIGNMENT#page3.tif	

ASSIGNMENT

Serial No. 13/188,992

Filed July 22, 2011

WHEREAS, Toshinari SASAKI, Hitomi SATO, Kosei NODA, Yuta ENDO, Mizuho IKARASHI, Keitaro IMAI, Atsuo ISOBE and Yutaka OKAZAKI

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME for which an application for Letters Patent of the United States of America has been executed by the undersigned on _____, and;

WHEREAS, Semiconductor Energy Laboratory Co., Ltd. of 398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan and its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America and its territories and for all foreign countries, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from

said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of ROBINSON INTELLECTUAL PROPERTY LAW OFFICE the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

In witness thereof, this Assignment has been executed by the undersigned on the date(s) opposite the undersigned name(s).

Date 11/2/2011 Signature Toshinari Sasaki
Name Toshinari SASAKI

Date 11/2/2011 Signature Hitomi Sato
Name Hitomi SATO

Date 11/3/2011 Signature Kosei Noda
Name Kosei NODA

Date 11/3/2011 Signature Yuta Endo
Name Yuta ENDO

Date 10/27/2011 Signature Mizuho IKARASHI
Name Mizuho IKARASHI

Date 10/13/2011 Signature Keitaro Imai
Name Keitaro IMAI

Date 11/02/2011 Signature Atsuo Isobe
Name Atsuo ISOBE

Date 11/2/2011 Signature Yutaka Okazaki
Name Yutaka OKAZAKI

This assignment should preferably be acknowledged before a United States Consul or Notary Public. If not, then the execution by the Inventor(s) should be witnessed has (have) invented certain new and useful improvements in by at least two other persons who should sign here.

Witness _____

Signature _____

Witness _____

Signature _____

Witness _____

Signature _____